

SPECIFICATION

Replace the abstract with the following replacement abstract.

—The invention(s) relates to a wafer test system including a circuit to communicate ~~means capable of communicating~~ an overdrive to a chuck, the chuck moving a wafer towards a probe head responsive to the overdrive, a circuit to measure ~~measuring~~ a contact resistance of at least one channel in each of a plurality of dies associated with the wafer using the probe head, a circuit to compute ~~computing~~ a per channel standard deviation responsive to measuring the contact resistance, a circuit to compare ~~comparing~~ the standard deviation on the at least one channel to a threshold, and a circuit to increase ~~increasing~~ the overdrive responsive to the comparison.—